

**SINGULATION METHODS AND SUBSTRATES  
FOR USE WITH SAME**

**Abstract of the Disclosure**

5           A circuit board substrate assembly includes a generally planar circuit board  
substrate material having a longitudinal axis extending along a length of the substrate  
material between a first end and a second end thereof. The circuit board substrate  
material further has a first edge and a second edge extending along the length of the  
circuit board substrate material between the first end and the second end. A plurality of  
10   openings are defined in the substrate material. Each opening extends between a first  
distance from the first edge of the circuit board substrate and a second distance from the  
second edge of the circuit board substrate. Further, each opening separates adjacent  
circuit forming regions lying along the longitudinal axis and has first and second  
opposing end portions. The first end portions of each opening lie along a first  
15   singulation axis of the substrate material parallel to the longitudinal axis and the second  
end portions of each opening lie along a second singulation axis of the substrate  
material parallel to the longitudinal axis. Removing interconnect material along the first  
singulation axis and second singulation axis provide for singulation of the circuit  
forming regions and any circuits thereof.

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